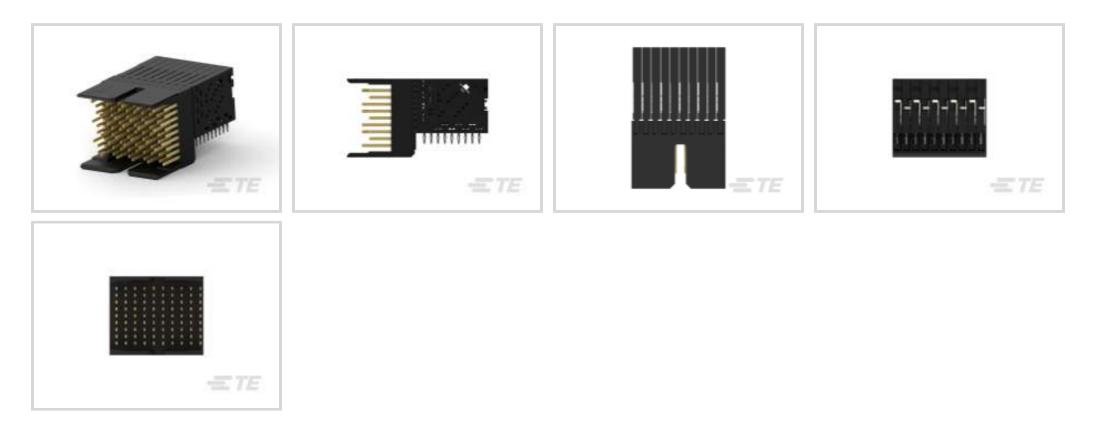


Z-PACK | Z-PACK TinMan

TE Internal #: 1934357-1 High Speed Backplane Connectors, 90 Position, Mating Alignment, Guide Slot Mating Alignment Type, 9 Row, 10 Column, PCB Mount Header, Z-PACK TinMan

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Connectors > PCB Connectors > Backplane Connectors > High Speed Backplane Connectors



Connector System: Board-to-Board Number of Positions: 90 Row-to-Row Spacing: 1.4 mm [.055 in] Mating Alignment: With

Mating Alignment Type: Guide Slot

Features



Product Type Features

Backplane Module Type	Center
Signal Arrangement	Differential
Connector System	Board-to-Board
PCB Connector Assembly Type	PCB Mount Header
Shroud Style	Partially Shrouded
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Pairs per Column	3
Number of Pairs	30
Stackable	No
Number of Signal Positions	60
Backplane Architecture	Co-Planar
Number of Positions	90
Number of Rows	9

High Speed Backplane Connectors, 90 Position, Mating Alignment, Guide Slot Mating Alignment Type, 9 Row, 10 Column, PCB Mount Header, Z-PACK TinMan



Number of Columns	10
PCB Mount Orientation	Right Angle
Electrical Characteristics	
Impedance	100 Ω
Operating Voltage	250 VAC
Signal Characteristics	
Differential Impedance	100 Ω
Number of Differential Pairs per Column	3
Data Rate	10 Gb/s
Body Features	
Shield Material	Phosphor Bronze
Primary Product Color	Black
Contact Features	
Contact Mating Area Length	6 mm[.236 in]
PCB Contact Termination Area Plating Material Thickness	.5 μm[20 μin]
Contact Type	Pin
Contact Mating Area Plating Material	Gold
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Rectangular
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Current Rating (Max)	.5 A
Termination Features	
Termination Post & Tail Length	2.2 mm[.087 in]
Termination Method to Printed Circuit Board	Through Hole - Press-Fit
Mechanical Attachment	
Guide Hardware	Without
Mating Retention	Without
PCB Mount Alignment	Without
PCB Mount Retention	With
PCB Mount Retention Type	Action/Compliant Tail
Mating Alignment	With

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High Speed Backplane Connectors, 90 Position, Mating Alignment, Guide Slot Mating Alignment Type, 9 Row, 10 Column, PCB Mount Header, Z-PACK TinMan



Mating Alignment Type	Guide Slot
Connector Mounting Type	Board Mount
Housing Features	
Number of Shrouded Sides	2
End Wall Location	Open
Housing Material	LCP (Liquid Crystal Polymer)
Centerline (Pitch)	1.9 mm[.075 in]
Dimensions	
Connector Length	19.15 mm
Connector Height	16 mm
Connector Width	28.8 mm
PCB Thickness (Recommended)	1.57 mm[.062 in]
PCB Hole Diameter	.47 mm
Row-to-Row Spacing	1.4 mm[.055 in]
Usage Conditions	
Operating Temperature Range	-65 – 90 °C[-85 – 194 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
Agency/Standard	UL
Approved Standards	UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Box & Tube, Tube
Packaging Features	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235)

High Speed Backplane Connectors, 90 Position, Mating Alignment, Guide Slot Mating Alignment Type, 9 Row, 10 Column, PCB Mount Header, Z-PACK TinMan



Candidate List Declared Against: JAN 2023 (233) Does not contain REACH SVHC

> Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Halogen Content

Solder Process Capability

Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series | Z-PACK TinMan

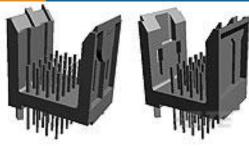


Customers Also Bought

High Speed Backplane Connectors, 90 Position, Mating Alignment, Guide Slot Mating Alignment Type, 9 Row, 10 Column, PCB Mount Header, Z-PACK TinMan







TE Part #5536504-3 2MM FB,ASY,096,SIG,HDR,EN,6.50

Documents

Product Drawings

Tinman R/A Header Assy 3x10 Open

English

CAD Files

Customer View Model ENG_CVM_CVM_1934357-1_B.2d_dxf.zip

English

3D PDF

3D

Customer View Model ENG_CVM_CVM_1934357-1_B.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1934357-1_B.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

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High Speed Backplane Connectors, 90 Position, Mating Alignment, Guide Slot Mating Alignment Type, 9 Row, 10 Column, PCB Mount Header, Z-PACK TinMan



High Speed Backplane Connectors catalog - Z-PACK TinMan High Speed, High Density Backplane Connector

English

Product Specifications Application Specification

English